C1 fluid comprising an ozone-containing gas and ultra pure water are sprayed onto substrates or semiconductor wafers in a treating chamber filled with ozone gas."

IN THE CLAIMS:

Please cancel claim 40 without prejudice.

Please amend claim 27 as follows:

27. (Twice Amended) A method for removing organic contaminants from a substrate, comprising the steps of:

Sub E1

contacting at least one side of said substrate with a liquid comprising water, ozone and an additive acting as a scavenger, wherein the proportion of said additive in said liquid is less than 1% molar weight of said liquid; and

C2

maintaining said liquid at a temperature less than the boiling point of said liquid.

Please add the following claims 51-60:

--51. A method for removing organic contaminants from a substrate, comprising the steps of:

Sub E2

C3

contacting at least one side of said substrate with a liquid comprising water, ozone and an additive acting as a scavenger, wherein said liquid is comprised substantially of water; and

maintaining said liquid at a temperature less than the boiling point of said liquid.

25 52. A method as recited in claim 51, wherein the proportion of said additive in said liquid is less than 1% molar weight of said liquid.

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26 ~~53~~. A method according to claim ~~52~~ 25, wherein the proportion of said additive in said liquid is less than 0.1% molar weight of said liquid.

27 ~~54~~. A method as recited in claim ~~51~~ 29, wherein the temperature of said liquid is between 60°C and 80°C.

28 ~~55~~. A method as recited in claim ~~51~~ 29, wherein said liquid is subjected to megasone agitation.

C13

29 ~~56~~. A method as recited in claim ~~51~~ 29, wherein the ozone is bubbled through the liquid.

30 ~~57~~. A method as recited in claim ~~51~~ 29, wherein said additive is acting as OH radical scavenger.

31 ~~58~~. A method as recited in claim ~~51~~ 29, further comprising the step of rinsing said substrate with a solution.

32 ~~59~~. A method as recited in claim ~~58~~ 31, wherein said solution comprises de-ionised water.

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